



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC0921NDI		<b>Issued</b>		14. August 2015		
<b>MA#</b>		MA001013776						
<b>Package</b>		PG-TISON-8-3		<b>Weight*</b>		101.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.917	0.90	0.90	9020	9020
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		101	
	non noble metal	zinc	7440-66-6	0.041	0.04		404	
	non noble metal	iron	7439-89-6	0.822	0.81		8082	
wire	non noble metal	copper	7440-50-8	33.360	32.82	33.68	328161	336748
	noble metal	gold	7440-57-5	0.068	0.07	0.07	667	667
	encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		905
plastics	plastics	epoxy resin	-	4.740	4.66		46626	
	inorganic material	silicondioxide	60676-86-0	41.187	40.50	45.25	405152	452683
leadfinish	non noble metal	tin	7440-31-5	1.122	1.10	1.10	11035	11035
plating	noble metal	silver	7440-22-4	0.186	0.18	0.18	1828	1828
solder	noble metal	silver	7440-22-4	0.036	0.04		353	
	non noble metal	tin	7440-31-5	0.029	0.03		282	
	non noble metal	lead	7439-92-1	1.370	1.35	1.42	13479	14114
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.01		52	
	non noble metal	zinc	7440-66-6	0.021	0.02		209	
	non noble metal	iron	7439-89-6	0.424	0.42		4174	
	non noble metal	copper	7440-50-8	17.228	16.95	17.40	169470	173905
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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